

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. KOMATSU, et al.  
Serial No.: 10/594,548  
Filed: SEPTEMBER 27, 2006  
For: HEAT-RESISTANT PHOTSENSITIVE RESIN  
COMPOSITION, METHOD FOR FORMING PATTERN USING  
THE COMPOSITION, AND ELECTRONIC PART  
Group AU: 1795  
Examiner: John S. Y. Chu  
Confirm. No.: 3540

**AMENDMENT**

**Mail Stop: AMD - FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 26, 2009

Sir:

In response to the Office Action mailed September 25, 2008, the period for response having been extended for one (1) month by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.